

In the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A bond pad for a flip chip package, suitable for an integrated circuit chip, comprising:

at least one slot extending along a first direction, which is perpendicular to a ~~radial~~ second direction radiating from the center of the integrated circuit chip.
2. (Original) The bond pad as claimed in claim 1, wherein the bond pad is located substantially at corners of the integrated circuit chip.
3. (Original) The bond pad as claimed in claim 1, wherein the patterns are arranged substantially in an array.
4. (Original) The bond pad as claimed in claim 1, wherein the bond pad is circular or rectangular.
5. (Original) The bond pad as claimed in claim 1, wherein the slot is rectangular.
6. (Original) The bond pad as claimed in claim 1, wherein the slot extends at least partially through the bond pad.

7. (Original) The bond pad as claimed in claim 1, wherein the slot extends down to the bottom of the bond pad.
8. (Currently Amended) A bond pad for a flip chip package, suitable for an integrated circuit chip, comprising:
a plurality of parallel slots located in the bond pad, each of the slots extending along a first direction, which is perpendicular to a ~~radial~~ second direction radiating from the center of the integrated circuit chip, wherein the bond pad is disposed ~~deposed~~ at the corner of the integrated circuit chip.
9. (Original) The bond pad as claimed in claim 8, wherein the bond pad is circular or rectangular.
10. (Original) The bond pad as claimed in claim 8, wherein the slot is rectangular.
11. (Original) The bond pad as claimed in claim 8, wherein the slot extends at least partially through the bond pad.
12. (Original) The bond pad as claimed in claim 8, wherein the slot extends down to the bottom of the bond pad.

13. (Original) A bond pad structure for a flip chip package, suitable for an integrated circuit chip, the integrated circuit chip having a rectangular shape, comprising:

a plurality of bond pads located in each of the quadrants of the integrated circuit chip, wherein each of the bond pads comprises at least one slot and each of the slots in the same quadrant extending along a direction which is substantially perpendicular to the diagonal lines of the integrated circuit chip passing through the quadrant in which it is located.

14. (Original) The bond pad as claimed in claim 13, wherein the patterns are arranged substantially in an array.

15. (Original) The bond pad as claimed in claim 13, wherein the slot is rectangular.

16. (Original) The bond pad as claimed in claim 13, wherein the slot extends at least partially through the bond pad.

17. (Original) The bond pad as claimed in claim 13, wherein the slot extends down to the bottom of the bond pad.

18. (Original) The bond pad as claimed in claim 13, wherein the bond pad is circular or rectangular.

19. (Currently Amended) A semiconductor device, comprising:
- a substrate;
 - a conductive layer, disposed on the substrate; and
 - at least one bond pad, disposed on the conductive layer, wherein the bond pad comprises at least one slot extending along a first direction, which is perpendicular to a ~~radial~~ second direction radiating from the center of the surface of the substrate.
20. (Currently Amended) The bond pad as claimed in claim 19, wherein the number of the bond pads located in ~~the~~ each quadrant[[s]] of the integrated circuit chip is more than one, and each of the slots in the same quadrant extending along a direction which is substantially perpendicular to the diagonal lines of the integrated circuit chip passing through the quadrant in which it is located.
21. (Original) The bond pad as claimed in claim 19, wherein the slot is rectangular.
22. (Original) The bond pad as claimed in claim 19, wherein the slot extends at least partially through the bond pad.
23. (Original) The bond pad as claimed in claim 19, wherein the slot extends down to the bottom of the bond pad.

24. (New) A bond pad for a flip chip package, suitable for an integrated circuit chip, comprising:

a slot extending along a first direction, which is perpendicular to a second direction radiating from the center of the integrated circuit chip,
wherein the slot is rectangular.

25. (New) The bond pad of claim 24, wherein the bond pad is deposited at the corner of the integrated circuit chip.

26. (New) The bond pad of claim 24, wherein the slot is one of a plurality of parallel slots located in the bond pad.

27. (New) The bond pad of claim 26, wherein each of the slots is rectangular.

28. (New) The bond pad of claim 26, wherein:

the slot is one of a plurality of slots located in quadrants of the integrated circuit chip; and
each of the slots in the same quadrant extending along a direction, which is substantially perpendicular to a diagonal line of the integrated circuit chip passing through the quadrant in which each of the slots is located.

29. (New) The bond pad of claim 28, wherein the integrated circuit chip is rectangular.

30. (New) A semiconductor device, comprising:
- a substrate;
 - a conductive layer disposed on the substrate; and
 - bond pads disposed on the conductive layer;
- wherein:
- at least one of the bond pads comprises at least one slot extending along a direction perpendicular to a radial direction from the center of the surface of the substrate;
 - each quadrant of the integrated circuit chip comprises at least two of the bond pads; and
 - slots in the same quadrant extend in a direction that is substantially perpendicular to the diagonal line of the integrated circuit chip passing through the quadrant in which each of the slots is located.
31. (New) The semiconductor device of claim 30, wherein the substrate is rectangular.
32. (New) The semiconductor device of claim 31, wherein the slots are rectangular.